Central™
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PCN #235
Notification Date:
April 28, 2022

Product / Process Change Notice

Parts Affected:
The CP710V wafer process

Extent of Change:
Wafer diameter has changed from 5” to 6”. In order to optimize the wire bond and die attach processes, slight adjustments were also made in the metallization thicknesses (see Table # 1).

Reason for Change:
Foundry process change

Effect of Change:
This change does not affect the form, fit, or function of any device; however, gross die quantities per wafer have increased.

Qualification:
Standard evaluation and qualifications were completed resulting in no performance differences compared to current product.

Effective Date of Change:
April 28, 2022

Table 1:

	Before Change	After Change
Die Size	26 x 26 MILS	26 x 26 MILS
Die Thickness	7.1 MILS	7.1 MILS
Base Bonding Pad Size	6.1 x 4.9 MILS	6.1 x 4.9 MILS
Emitter Bonding Pad Size	5.2 x 5.2 MILS	5.2 x 5.2 MILS
Top Side Metalization	Al – 30,000Å	Al – 26,000Å
Back Side Metalization	Au – 9,000Å	Au – 12,000Å
Scribe Alley Width	2.2 MILS	2.2 MILS
Wafer Diameter	5 INCHES	6 INCHES
Gross Die Per Wafer	25,214	35,375

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Part Numbers Affected:

CP710V-BC393-WN	CP710V-CMPTA96-WN	CP710V-MPSA92-WN
CP710V-CEN1153-CT	CP710V-CZTA94-CT	CP710V-2N5415-CT
CP710V-CEN1153-WN	CP710V-HCEN2031-CM	CP710V-2N5415-CT20
CP710V-CEN1393-CTJ	CP710V-HCEN2031-WN	CP710V-2N5415-WN
CP710V-CEN1393-WN	CP710V-HMPSA92-CM	CP710V-2N5416-CT
CP710V-CJD350-CT	CP710V-KCEN2032-CM	CP710V-2N5416-WN
CP710V-CJD350-WN	CP710V-KCEN2032-WN	CP710V-2N6520-CT
CP710V-CMPTA94-CT	CP710V-MPSA92-CM	CP710V-2N6520-WN
CP710V-CMPTA94-WN	CP710V-MPSA92-CT	
CP710V-CMPTA96-CT	CP710V-MPSA92-CT20	